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- State-of-the-Art BiCMOS Design Significantly Reduces I_{CCZ}
- Full Parallel Access for Loading
- Buffered Control Inputs
- 3-State Bus-Driving Inverted Outputs
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Plastic and Ceramic 300-mil DIPs (J, N)

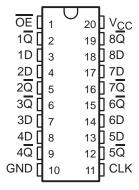
description

The 'BCT534 is an 8-bit flip-flop with 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. It is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

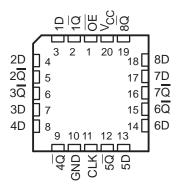
The eight flip-flops of the 'BCT534 are edge-triggered D-type flip-flops. On the positive transition of the clock, the \overline{Q} outputs will be set to the complement of the logic levels that were set up at the data (D) inputs. The 'BCT534 provides inverted data at its outputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components.

SN54BCT534 . . . J OR W PACKAGE SN74BCT534 . . . DW OR N PACKAGE (TOP VIEW)



SN54BCT534 . . . FK PACKAGE (TOP VIEW)



The output-enable (\overline{OE}) input does not affect the internal operations of the flip-flop. Previously stored data can be retained or new data can be entered while the outputs are in the high-impedance state.

The SN54BCT534 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74BCT534 is characterized for operation from 0° C to 70° C.

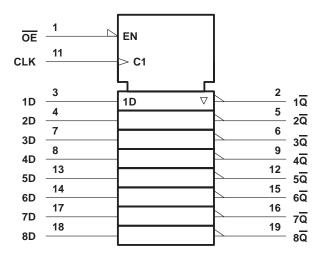
FUNCTION TABLE (each flip-flop)

	INPUTS	OUTPUT	
ŌĒ	CLK	D	Q
L	\uparrow	Н	L
L	\uparrow	L	Н
L	H or L	Χ	\overline{Q}_0
Н	X	Χ	Z



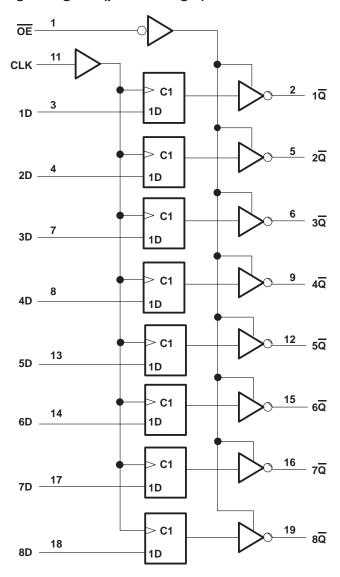
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logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		$\ldots \ldots -0.5$ V to 7 V
Input voltage range, V _I (see Note 1)		
Voltage range applied to any output in	the disabled or power-off state, V_{C}	– 0.5 V to 5.5 V
Voltage range applied to any output in	the high state, V_O $\dots \dots$	$\dots - 0.5 \text{ V to V}_{CC}$
Input clamp current		30 mA
Current into any output in the low state	: SN54BCT534	96 mA
	SN74BCT534	128 mA
Operating free-air temperature range:	SN54BCT534	– 55°C to 125°C
	SN74BCT534	0°C to 70°C
Storage temperature range		– 65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

recommended operating conditions

		SN54BCT534		SN	UNIT			
		MIN	NOM	MAX	MIN	NOM	MAX	UNII
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
lıK	Input clamp current			-18			-18	mA
ІОН	High-level output current			-12			-15	mA
loL	Low-level output current			48			64	mA
TA	Operating free-air temperature	-55		125	0		70	°C



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN	54BCT5	34	SN74BCT534			UNIT
PARAMETER	le:	TEST CONDITIONS		TYP†	MAX	MIN	TYP	MAX	UNII
VIK	$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA			-1.2			-1.2	V
		$I_{OH} = -3 \text{ mA}$	2.4	3.3		2.4	3.4		
Voн	V _{CC} = 4.5 V	$I_{OH} = -12 \text{ mA}$	2	3.2					V
		$I_{OH} = -15 \text{ mA}$				2	3.1		
Vo.	V _{CC} = 4.5 V	$I_{OL} = 48 \text{ mA}$		0.38	0.55				V
VOL	VCC = 4.5 V	$I_{OL} = 64 \text{ mA}$					0.42	0.55	٧
lį	$V_{CC} = 5.5 \text{ V},$	$V_{I} = 5.5 \text{ V}$			0.4			0.4	mA
lін	$V_{CC} = 5.5 \text{ V},$	$V_{I} = 2.7 \text{ V}$			20			20	μΑ
I _{IL}	$V_{CC} = 5.5 \text{ V},$	$V_{I} = 0.5 V$			-0.6			-0.6	mA
los [‡]	$V_{CC} = 5.5 \text{ V},$	V _O = 0	-100		-225	-100		-225	mA
lozh	$V_{CC} = 5.5 \text{ V},$	V _O = 2.7 V			50			50	μΑ
lozL	$V_{CC} = 5.5 \text{ V},$	V _O = 0.5 V			-50			-50	μΑ
ICCL	$V_{CC} = 5.5 \text{ V},$	V _O = Open		38	55		38	55	mA
Іссн	$V_{CC} = 5.5 \text{ V},$	V _O = Open		5	8		5	8	mA
Iccz	$V_{CC} = 5.5 \text{ V},$	V _O = Open		4.5	7		4.5	7	mA
Ci	V _{CC} = 5 V,	$V_I = V_{CC}$ or GND		6			6		pF
Co	V _{CC} = 5 V,	$V_O = V_{CC}$ or GND		10			10		pF

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

			V _{CC} :	= 5 V, 25°C	SN54B	CT534	SN74B	CT534	UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX		
fclock	f _{clock} Clock frequency		0	77	0	70	0	77	MHz	
	Pulse duration	CLK high	6		6		6		ns	
t _W	r dise duration	CLK low	7		7		7		113	
	Catura tima hafana OLKA	Data high	6		6		6		no	
t _{su}	Setup time before CLK↑	Data low	9.5		9.5		9.5		ns	
4.	Hold time after CLK↑	Data high	0		0		0		no	
th	HOID LITTLE AILER CLAT	Data low	1		1		1		ns	

[‡] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

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switching characteristics (see Note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _I R.	CC = 5 V = 50 p 1 = 500 s 2 = 500 s 1 = 25°C	F, Ω, Ω,	C _L R ₁ R ₂	= 50 pF = 500 £ = 500 £	2,	V,	UNIT
			′1	BCT534		SN54B	CT534	SN74B	CT534	
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}			77			70		77		MHz
t _{PLH}	CLK	Ια	3.3	6.7	9.6	3.3	12.8	3.3	11.4	ns
t _{PHL}		g	3.5	6.2	8.8	3.5	11	3.5	10	115
^t PZH	ŌĒ	<u>α</u>	3.9	7.6	10.3	3.9	13.1	3.9	12.5	ne
t _{PZL}		ď	4.6	8.2	11.1	4.6	13.7	4.6	13.3	ns
t _{PHZ}	ŌĒ	Q	2.6	4.7	6.7	2.6	8	2.6	7.4	ne
tPLZ	OE .	Q	1.8	4.1	6.1	1.8	7.8	1.8	6.9	ns

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. NOTE 2: Load circuits and voltage waveforms are shown in Section 1.







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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9074701MRA	OBSOLETE	CDIP	J	20	TBD	Call TI	Call TI
SN74BCT534DW	OBSOLETE	SOIC	DW	20	TBD	Call TI	Call TI
SN74BCT534DWR	OBSOLETE	SOIC	DW	20	TBD	Call TI	Call TI
SN74BCT534N	OBSOLETE	PDIP	N	20	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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